

	Type	L #	Hits	Search Text	DBs
1	BRS	L5	603	257/737.ccls.	USPAT
2	BRS	L6	444	257/780.ccls.	USPAT
3	BRS	L7	1	5656863.pn.	USPAT
4	BRS	L8	1	5925931.pn.	USPAT
5	BRS	L9	48146	CSP and (ball or bump) and solder	USPAT
6	BRS	L10	48073	(chip adj size adj package) and (ball or bump) and solder	USPAT
7	BRS	L11	8403	(chip adj size adj package) and (ball or bump) and solder and metal and pad	USPAT
8	BRS	L12	98	(chip adj size adj package) and (ball or bump) and solder and metal and pad	USPAT
9	BRS	L13	12	(chip adj size adj package) and (ball or bump) and solder and metal and pad and micron	USPAT
10	BRS	L14	43	257/737.ccls. and CSP	USPAT
11	BRS	L15	0	257/737.ccls. and CSP and microbump	USPAT
12	BRS	L16	4	257/737.ccls. and CSP and micron	USPAT
13	BRS	L17	6	257/737.ccls. and microbump	USPAT
14	BRS	L19	230	257/737.ccls.	EPO; JPO; IBM TDB
15	BRS	L21	98	257/780.ccls.	EPO; JPO; IBM TDB
16	BRS	L20	1	(chip adj size adj package) and (ball or bump) and solder and metal and pad	EPO; JPO; IBM TDB
17	BRS	L18	75	L12 and via	USPAT